Product Change Notification - ASER-27VHSG893

Date:
14 Jan 2020
Product Category:
Ethernet Switches
Affected CPNs:

Notification subject:
CCB 3867 Final Notice: Qualification of ASE as a new assembly site for selected Micrel KSZ8842 device family available in 100L LFBGA (9x9x1.38 mm) package.
Notification text:

PCN Status:
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of ASE as a new assembly site for selected Micrel KSZ8842 device family available in 100L LFBGA (9x9x1.38 mm) package.

Pre Change:
Assembled at OSE assembly site using 2300 die attach and E770 molding compound.

Post Change:
Assembled at ASE assembly site using 2100 die attach and KE-G1250NAS molding compound.

Pre and Post Change Summary:

		Pre Change	**Post Change**
Assembly Site		Orient Semiconductor Electronics, Ltd (OSE)	Advanced Semiconductor Engineering, Inc. (ASE)
Wire material		Au	Au
Die attach material		2300	2100
Molding compound material		E770	KE-G1250NAS
Substrate material	Core	HL832NX	HL832NX
	Solder Mask	AUS308	AUS308
	Solder Mask Thickness	25 ± 10µm	30 ± 10µm
Solder Ball		SAC305	SAC305

Impacts to Data Sheet:

None.

Change Impact:
None.

Reason for Change:
To improve manufacturability by qualifying ASE as a new assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
February 17, 2020 (date code: 2008)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2019					-->	January 2020					February 2020			
Workweek	27	28	29	30	31		1	2	3	4	5	6	7	8	9
Initial PCN Issue Date		X													
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date														X	

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:
July 11, 2019: Issued initial notification.
July 15, 2019: Replaced inaccurate qualification plan with the correct document. Reissued initial notification.
January 14, 2019: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 17, 2020. Updated the Subject and Description to add the affected device families.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):
PCN_ASER-27VHSG893_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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